Bill of Materials

	SCM	SCC	Remarks
Die Attach	Ablestik 3230	Ablestik 3230	Same BOM
Wire type	Gold MKE UR2	Gold MKE UR2	
Mold Compound	Sumitomo G770	Sumitomo G770	
Lead Finish	Matte Sn	Matte Sn	

Reliability Qualification Plan for LFCSP Package at STATS ChipPAC China (SCC)

QUALIFICATION PLAN			
Test	**Conditions**	**Sample Size**	**Expected Completion Date**
Highly Accelerated Stress Test (HAST)*	JEDEC *JESD22-A110*	**3 x 82**	April 2014
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	**3 x 82**	April 2014
Autoclave (AC)*	JEDEC *JESD22-A102*	**3 x 82**	April 2014
Solder Heat Resistance (SHR)*	*ADI-0049*	**3 x 11**	April 2014
High Temperature Storage (HTS)	JEDEC *JESD22-A103*	**1 x 82**	April 2014
Field Induced Charged Device Model (FICDM)	JEDEC *JESD22-C101*	**3/Voltage**	April 2014

*These samples will be subjected to preconditioning (per J-STD-020 Level 3) prior to the start of the stress test. Level 3 preconditioning consists of the following: Bake: 24 hrs @ 125ºC, Soak: Unbiased Soak: 192 hrs @ 30ºC, 60%RH, Reflow: 3 passes through an oven with a peak temperature of 260ºC.

ANALOG DEVICES | Everywhere